DAFTAR PUSTAKA

[1] S. Arifin and F. Samopa, "Analysis of Churn Rate Significantly Factors in Telecommunication Industry Using Support Vector Machines Method," *J. Phys. Conf. Ser.*, vol. 1108, no. 1, pp. 0–7, 2018.

[2] F. Castanedo, "Using Deep Learning to Predict Customer Churn in a Mobile Telecommunication Network," pp. 1–8, 2014.

[3] S. B. & C. Nass, "Emotions in human–computer interaction," in *Face-To-Face Communication over the Internet*, no. March, 2012, pp. 213–236.

[4] W. Suharso, A. Djunaidy, and K. Sukolilo, "Analisis Customer Churn Menggunakan Bayesian Belief Network (Studi Kasus : Perusahaan Layanan Internet)," pp. 323–335, 2012.

[5] Muhammad Arifin, "Business intelligence Untuk

Prediksi Customer Churn Telekomunikasi," *Pros. SNATIF*, vol. 1, no. Business Intelligence, pp. 279–286, 2009.

[6] R. Dass and R. Jain, "Association for Information Systems AIS Electronic Library (AISeL) An Analysis on the factors causing telecom churn: First Findings," 2011.

[7] A. F. dan A. Y. Siti Helmiyah1*, "Ekstraksi Ciri Emosi Manusia Berdasarkan Ucapan Menggunakan Mel-Frequency Cepstral Coefficients (MFCC)," in *Prosiding SNST ke-9 Tahun 2018*, 2018, pp. 31–36.

[8] Z. Huang, L. Chen, and M. Harper, "An open source prosodic feature extraction tool," *Proc Lang. Resour. ...*, pp. 2116–2121, 2006.

[9] J. Rong, Y. P. P. Chen, M. Chowdhury, and G. Li, "Acoustic features extraction for emotion recognition," *Proc. - 6th IEEE/ACIS Int. Conf. Comput. Inf. Sci. ICIS*

2007; 1st IEEE/ACIS Int. Work. e-Activity, IWEA 2007, no. January, pp. 419–424, 2007.

[10] W. F. and J. G. T. R. Cowie, E. Douglas-Cowie, N. Tsapatsoulis, G. Votsis, S. Kollias, "Emotion Recognition in Human-Computer Interaction," *IEEE Signal Processing Magazine*, no. January, 2001.

[11] D. Heckerman, "A Tutorial on Learning Bayesian Networks," *Innov. Bayesian Networks*, no. October 2008, 2008.

[12] Y. A. Wicaksono, H. A. Santoso, and D. Earthquake, "Implementasi Metode Bayesian Network Untuk Decision Support System Pada Mini Detector Earthquake," *Semin. Nas. Teknol. Inf. dan Multimed. 2016*, pp. 6–7, 2016.